

# N-Channel 100-V (D-S) MOSFET

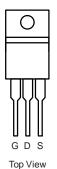
PRODUCT SUMMARY					
V <sub>(BR)DSS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)			
100	0.127at V <sub>GS</sub> = 10 V	18			

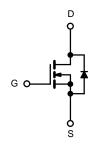
### **FEATURES**

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R<sub>g</sub> Tested









N-Channel MOSFET

## APPLICATIONS

•	Isolated	DC/DC	Converters
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<b>ABSOLUTE MAXIMUM RATINGS</b>	T <sub>C</sub> = 25 °C, unless oth	erwise noted		_
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
Continuous Drain Current (T <sub>.1</sub> = 175 °C)	T <sub>C</sub> = 25 °C	1-	18	
Continuous Diam Current (1j = 175 C)	T <sub>C</sub> = 125 °C	I <sub>D</sub>	15	
Pulsed Drain Current		I <sub>DM</sub>	68	_ A
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	18	
Single Pulse Avalanche Energy <sup>b</sup>	L=0.11IIII	E <sub>AS</sub>	200	mJ
Mariana Barra Biratia da	T <sub>C</sub> = 25 °C	l p	105	10/
Maximum Power Dissipation <sup>b</sup>	T <sub>A</sub> = 25 °C <sup>d</sup>	P <sub>D</sub>	3.75	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) <sup>d</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.4	C/VV	

### Notes:

- a. Package limited.
- b. Duty cycle  $\leq$  1 %.
- c. See SOA curve for voltage derating.
- d. When Mounted on 1" square PCB (FR-4 material).



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	100			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.127			
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.130		Ω	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.170			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A	25			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			1300		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		260			
Reverse Transfer Capacitance	C <sub>rss</sub>			110			
Total Gate Charge <sup>c</sup>	$Q_g$				28		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 65 \text{ A}$			4.8	nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$				15		
Gate Resistance	$R_{g}$		0.5	1.7	3.3	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8			
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 100 \text{ V}, R_{L} = 1.5 \Omega$		120		ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 65 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		25			
Fall Time <sup>c</sup>	t <sub>f</sub>			50			
Source-Drain Diode Ratings and Cha	aracteristics 7	C <sub>C</sub> = 25 °C <sup>b</sup>					
Continuous Current	Is			18			
Pulsed Current	I <sub>SM</sub>			68		A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 65 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			130	200	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 50 A, di/dt = 100 A/μs		8	12	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	_		0.52	1.2	μC	

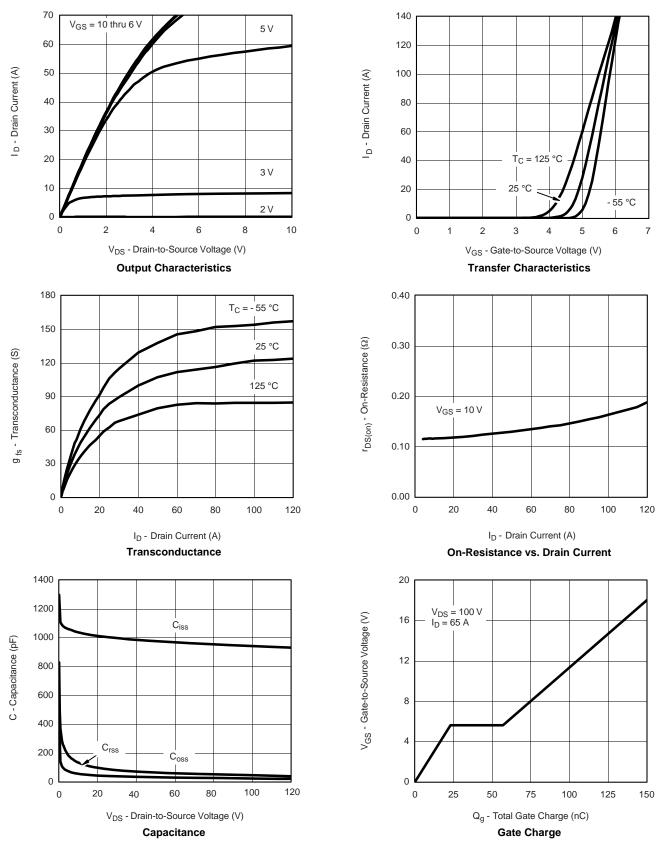
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

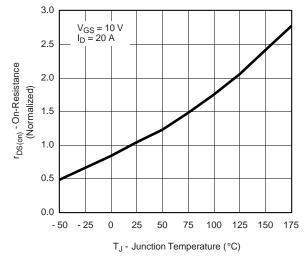


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

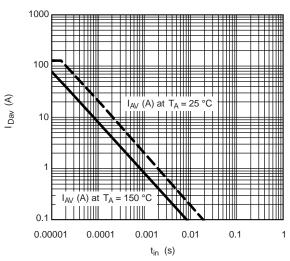




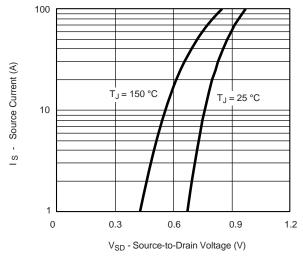
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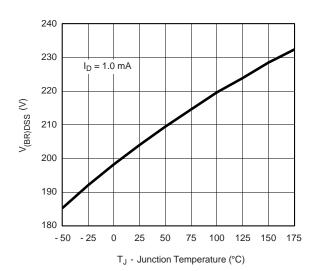
On-Resistance vs. Junction Temperature



**Avalanche Current vs. Time** 



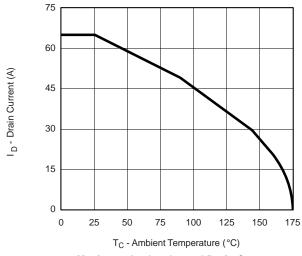
Source-Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature

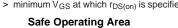


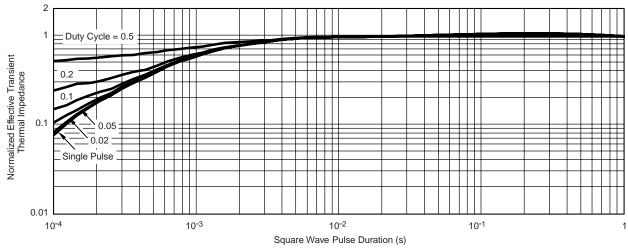
### THERMAL RATINGS



1000 r<sub>DS(on)</sub> Limited 10 µs 100 I<sub>D</sub> - Drain Current (A) 10 T<sub>C</sub> = 25 °C Single Pulse 10 ms 100 ms DC 0.1 0.1 100 1000 10 V<sub>DS</sub> - Drain-to-Source Voltage (V) \*  $V_{GS}$  > minimum  $V_{GS}$  at which  $r_{DS(on)}$  is specified

**Maximum Avalanche and Drain Current** vs. Case Temperature

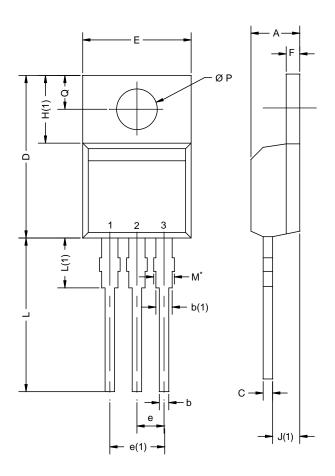




Normalized Thermal Transient Impedance, Junction-to-Case



# **TO-220AB**



	MILLIM	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØР	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

#### Notes

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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